## Kamlesh Joshi

List of Publications by Year in descending order

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10 papers	94 citations	1937685 4 h-index	1588992 8 g-index
10 all docs	10 docs citations	10 times ranked	81 citing authors

#	Article	IF	CITATIONS
1	Ultra thin silicon wafer slicing using wire-EDM for solar cell application. Materials and Design, 2017, 124, 158-170.	7.0	45
2	Microstructural Characterization of Thermal Damage on Silicon Wafers Sliced Using Wire-Electrical Discharge Machining. Journal of Manufacturing Science and Engineering, Transactions of the ASME, 2018, 140, .	2.2	17
3	Identification of wire electrical discharge machinability of SiC sintered using rapid hot pressing technique. Ceramics International, 2020, 46, 17261-17271.	4.8	11
4	Surface Quality and Contamination on Si Wafer Surfaces Sliced Using Wire-Electrical Discharge Machining. Journal of Engineering Materials and Technology, Transactions of the ASME, 2019, 141, .	1.4	7
5	Numerical Modelling of Wire-EDM for Predicting Erosion Rate of Silicon. Journal of the Institution of Engineers (India): Series C, 2017, 98, 63-73.	1.2	4
6	Influence of open voltage and servo voltage during Wire-EDM of silicon carbides. Procedia CIRP, 2020, 95, 285-289.	1.9	4
7	Surface integrity and wafer-thickness variation analysis of ultra-thin silicon wafers sliced using wire-EDM. Advances in Materials and Processing Technologies, 2019, 5, 512-525.	1.4	3
8	Experiments with Miniature Wire EDM for Silicon. Procedia CIRP, 2020, 95, 296-301.	1.9	2
9	Effect of Deposition Parameters & Molybdenum Percentage on Nickel-Molybdenum Alloy Coatings. Advanced Materials Research, 0, 585, 493-497.	0.3	1
10	Comparative electrical characterization of spark-erosion of silicon and steel as a base and its implications on equivalent circuit. Materials Science in Semiconductor Processing, 2022, 137, 106199.	4.0	0